



## Features

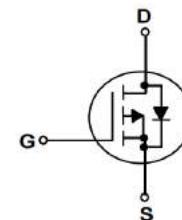
- P-Channel
- High Power and current handing capability
- Lead free product is acquired
- 100% EAS Tested

$V_{DS}$	-30	V
$R_{DS(on),TYP}$ @ $V_{GS}=-10$ V	2.8	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	4.6	mΩ
$I_D$	-105	A

DNF5x6



Part ID	Package Type	Marking	Packing
ZT028P03G	DFN5x6	ZT028P03G	5000pcs/reel



**Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V	
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	-416	A
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous	$T_c=25^\circ\text{C}$	-105	A
		$T_c=100^\circ\text{C}$	-65	A
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	58	W
		$T_c=100^\circ\text{C}$	23	W
$R_{zC}$	Thermal Resistance-Junction to Case	2.15	°C/W	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 2)	578	mJ	



**Electrical Characteristics  $T_J=25$  unless otherwise noted**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J=25^\circ\text{C}</math> (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	--	--	-1	$\mu\text{A}$
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0	-1.7	-2.5	V
R <sub>D(on)</sub>	Drain-Source On-State Resistance (Note 4)	$V_{GS}=-10\text{V}, I_D=-20\text{A}$	--	2.8	3.5	$\text{m}\Omega$
R <sub>D(on)</sub>	Drain-Source On-State Resistance	$V_{GS}=-4.5\text{V}, I_D=-20\text{A}$	--	4.6	5.9	$\text{m}\Omega$
g <sub>FS</sub>	Forward Transconductance (Note 4)	$V_{DS}=-5\text{V}, I_D=-20\text{A}$	--	65	--	S

**Dynamic Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	--	6995	--	pF
C <sub>oss</sub>	Output Capacitance		--	820	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	540	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	2.2	--	$\Omega$
Q <sub>g</sub>	Total Gate Charge		--	130	--	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	--	12	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	31	--	nC

**Switching Characteristics (Note 5)**

T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-15V, R <sub>L</sub> =0.75 $\Omega$ , R <sub>G</sub> =3 $\Omega$ , V <sub>GS</sub> =-10V	--	14	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	13	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	65	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	37	--	ns

**Source-Drain Diode Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

I <sub>SD</sub>	Source-Drain Current (Body Diode)		--	--	-105	A
V <sub>SD</sub>	Forward on voltage	I <sub>S</sub> = -20A, V <sub>GS</sub> =0V	--	--	-1.2	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25, I <sub>F</sub> =-20A, V <sub>GS</sub> =0V di/dt=100A/ $\mu\text{s}$	--	30	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	40	--	nC

Note :

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.E<sub>AS</sub> condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=15V, V<sub>GS</sub>=-10V, R<sub>G</sub>=25 $\Omega$ , L=0.5mH.

3.Repetitive Rating: Pulse width limited by maximum junction temperature.



## Typical Electrical And Thermal Characteristics (Curves)

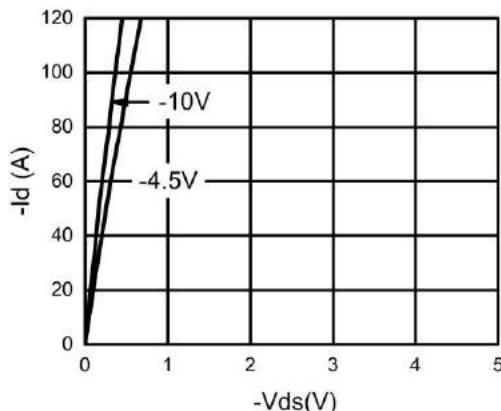


Figure 1. Output Characteristics

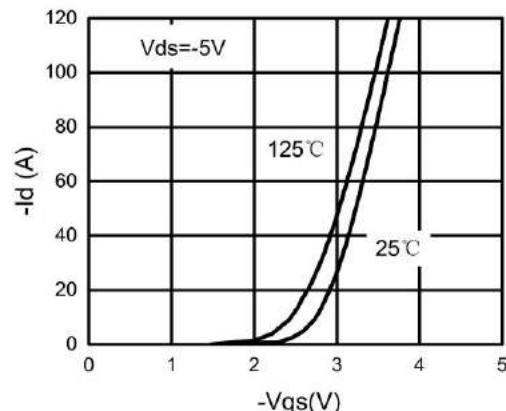


Figure 4. Transfer Characteristics

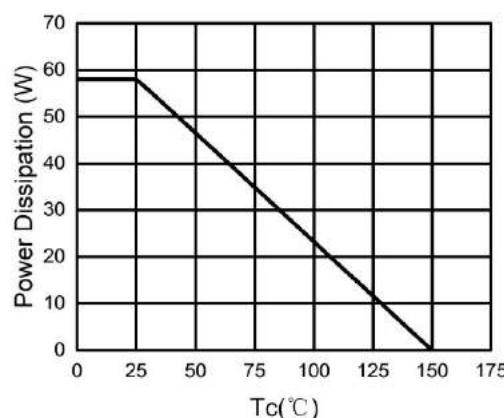


Figure 2. Power Dissipation

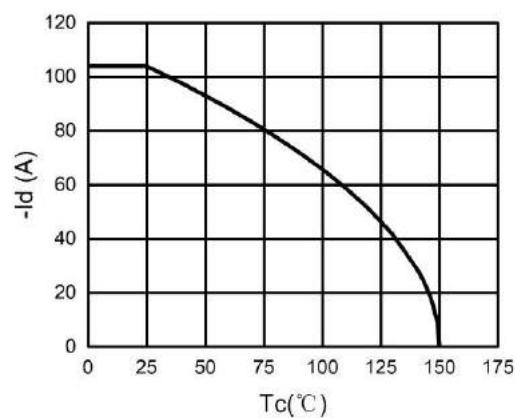


Figure 5. Drain Current

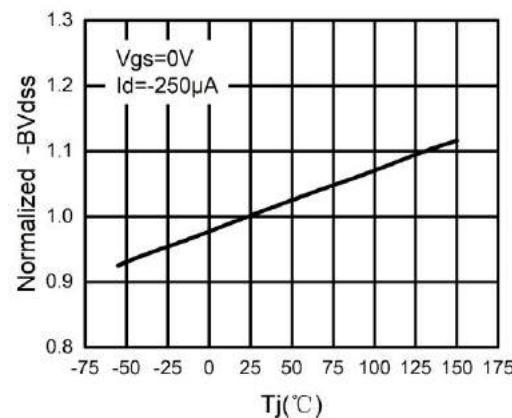


Figure 3.  $BV_{dss}$  vs Junction Temperature

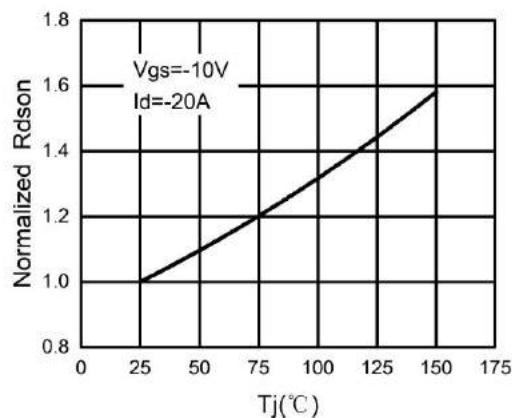


Figure 6.  $R_{DS(\text{ON})}$  vs Junction Temperature

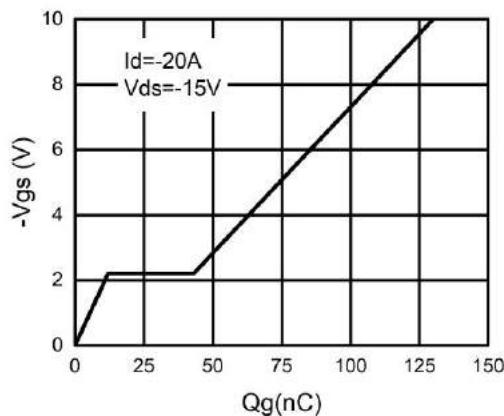


Figure 7. Gate Charge Waveforms

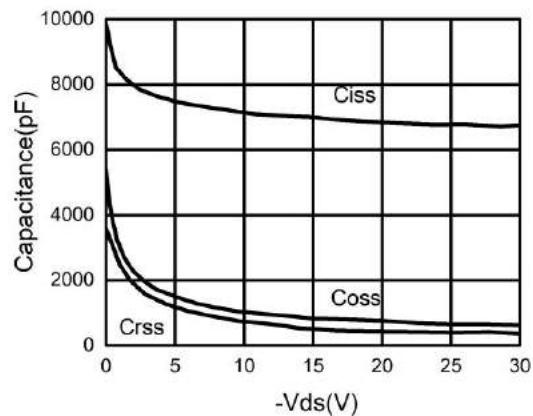


Figure 9. Capacitance

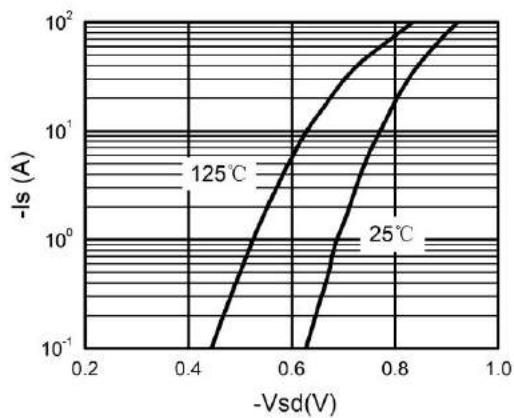


Figure 8. Body-Diode Characteristics

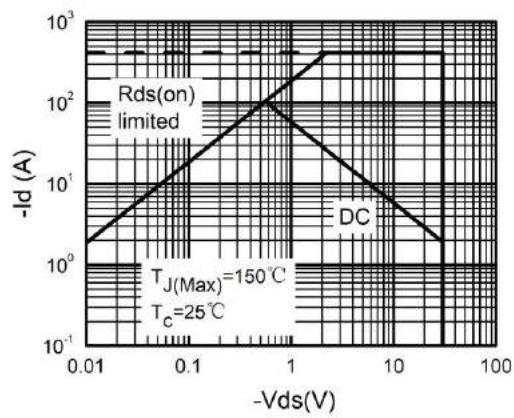
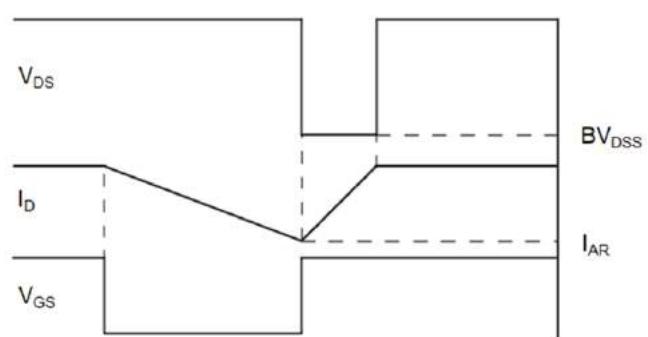
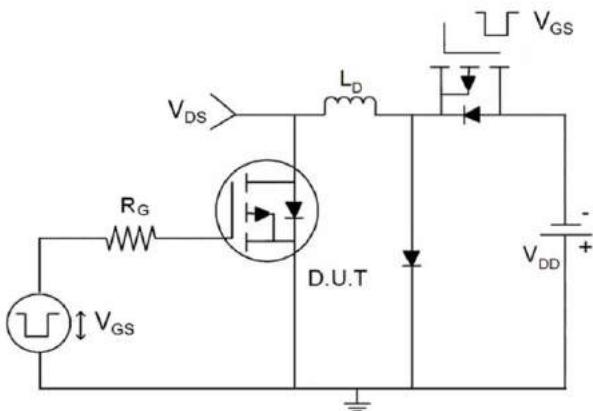


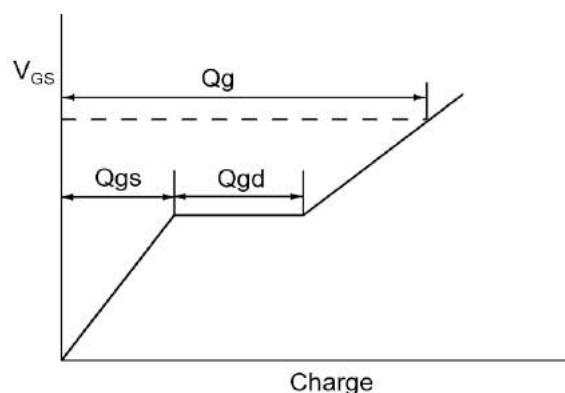
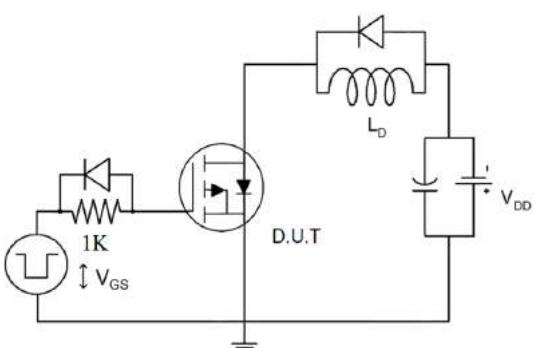
Figure 10. Maximum Safe Operating Area

## Test Circuit

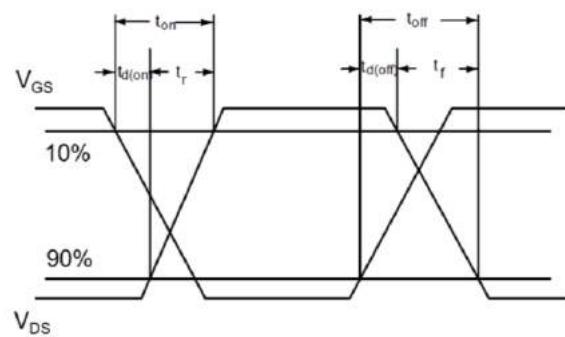
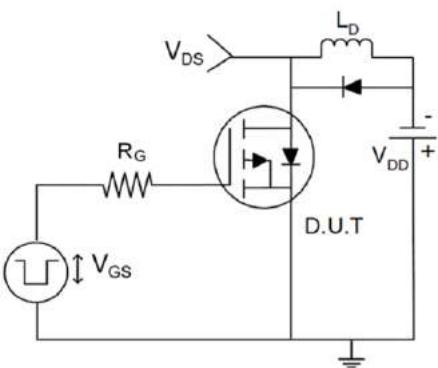
### 1) $E_{AS}$ Test Circuits



### 2) Gate Charge Test Circuit

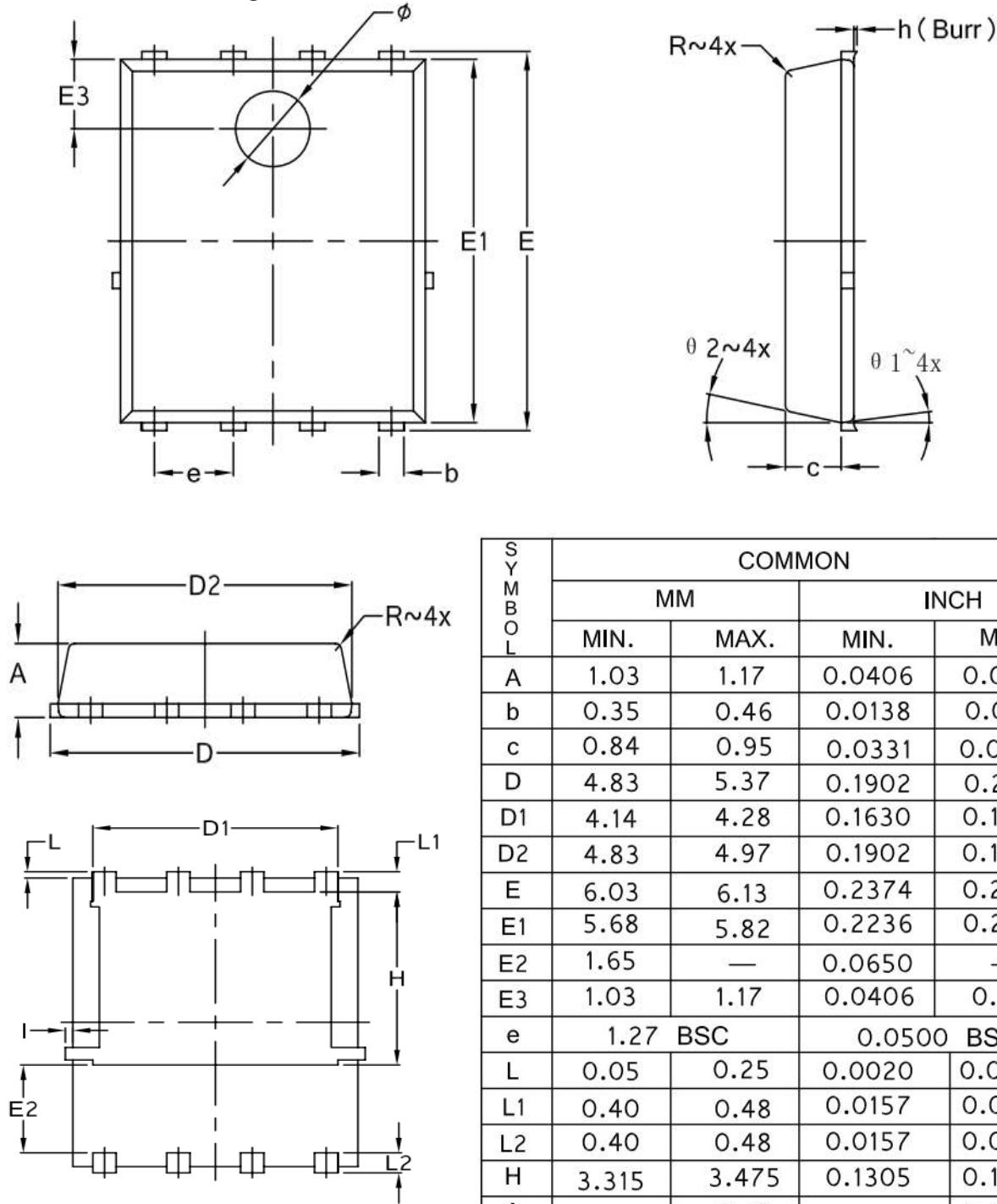


### 3) Switch Time Test Circuit





## DFN5x6-8L Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.35	0.46	0.0138	0.0181
c	0.84	0.95	0.0331	0.0374
D	4.83	5.37	0.1902	0.2114
D1	4.14	4.28	0.1630	0.1685
D2	4.83	4.97	0.1902	0.1957
E	6.03	6.13	0.2374	0.2413
E1	5.68	5.82	0.2236	0.2291
E2	1.65	—	0.0650	—
E3	1.03	1.17	0.0406	0.0461
e	1.27	BSC	0.0500	BSC
L	0.05	0.25	0.0020	0.0098
L1	0.40	0.48	0.0157	0.0189
L2	0.40	0.48	0.0157	0.0189
H	3.315	3.475	0.1305	0.1368
I	—	0.16	—	0.0063
$\phi$	1.13	1.27	0.0445	0.0500
R	0.10		0.0039	
$\theta_1$	7° REF		7° REF	
$\theta_2$	12° REF		12° REF	
h	0.08 MAX		0.0031	

## Customer Service

Sales and Service:

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